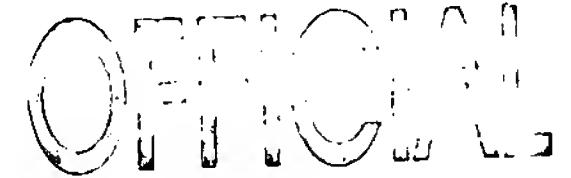


JUN 16 2004

Patent**Customer No.: 31561
Docket No. 9249-US-PA
Application No.: 10/604,791****IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Applicant : Lee et al.
Application No. : 10/604,791
Filed : 2003/08/18
For : SEMICONDUCTOR PACKAGE MODULE AND
MANUFACTURING METHOD THEREOF
Art Unit : 2811
Examiner : NGUYEN, CUONG QUANG

**TRANSMITTAL LETTER**

002-1-703-872-9306

(Via fax: 3 pages, followed by confirmation copy via courier)

Assistant Commissioner for Patents
Arlington, Virginia 22202

Dear Sirs,

In response to the Office Action dated June 1, 2004, please find the relevant paper in response to paper No. 20040526. Following the fax transmission, a hard copy via courier will also be forwarded to the Office.

Enclosed documents via courier will include:

- Response to Restriction Requirement in (1) pages
- Fax confirmation report
- Prepaid return postcard

I believe that no fee is incurred. However, the Commissioner is authorized to charge any fees required in connection with the filing of this paper to account No. 50-2620 (Order No.: 9249-US-PA)

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

Patent

Customer No.: 31561
Docket No. 9249-US-PA
Application No.: 10/604,791

Respectfully Submitted,
JIANQ CHYUN Intellectual Property Office

Date: Jun 16, 2004

By: Belinda Lee
Belinda Lee
Registration No.: 46,863

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